

GEL SEAL



Application:

ISP's Gel Seal is a re-enterable cold curing 2 component non urethane encapsulating gel. The resin is suitable for telecommunication applications to avoid damage caused by moisture. It is also suitable for insulation of low voltage connections and for the sealing of other electronic parts, especially when no mechanical stress is allowed (even at very low temperatures).

Properties:

- Free of Isocyanides, epoxides and silicones
- Not classified according to the EC regulations
- Medium viscosity while pouring
- Good adhesion to metals, minerals and many plastics
- Excellent hydrophobic behavior
- Seals any enclosure to IP68

Technical specifications:

Mixture	Mixing ratio resin/hardener	1:1
	Viscosity/ 20°C	approx. 1.000 cps
	Color	transparent amber
	Density	0,91 g/cm ³
	Pot life/ 20°C	approx. 20 min.
	Gel time/ 20°C	approx. 50 min.
	Temperature resistance	long time 80°C short time 120 °C
	Elongation at break	95 %
	Corrosion of copper (MS17000, section 1139)	non corrosive
	Insulation resistance @ 500 V DC	1,2 x 10 ¹² ohm
	Volume resistivity @ 500 V DC	0,6 x 10 ¹³ ohm.cm
	Water sensitivity (TA-NWT-000354)	0%
	Water absorption (ASTM D570)	0,36 %
	Chemical resistance against Mineral oil, 2n H2SO4, CaCO3- Solution	no visible degradation

Subject to change without notice

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